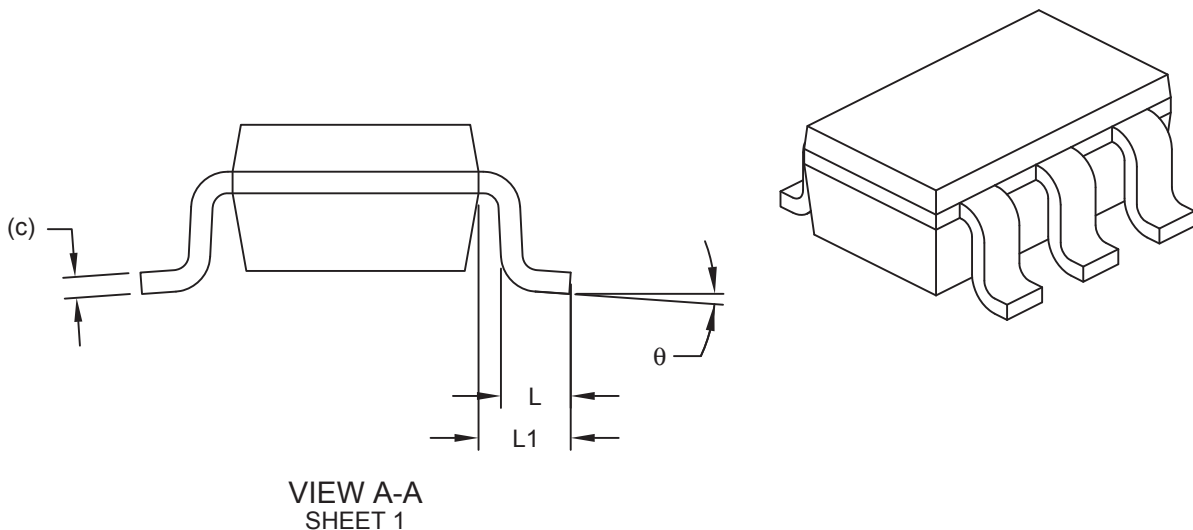


5-Lead Plastic Thin Small Outline Transistor (NMB) [TSOT] Atmel Legacy Global Package Code TSZ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Leads	N	5			
Pitch	e	0.95 BSC			
Outside lead pitch	e1	1.90 BSC			
Overall Height	A	-	-	-	1.10
Molded Package Thickness	A2	0.70	0.90	1.00	
Standoff	A1	-	-	-	0.10
Overall Width	E	2.80 BSC			
Molded Package Width	E1	1.60 BSC			
Overall Length	D	2.90 BSC			
Foot Length	L	0.30	-	0.60	
Footprint	L1	0.60 REF			
Foot Angle	θ	0°	-	8°	
Lead Thickness	c	0.08	-	0.20	
Lead Width	b	0.30	-	0.50	

Notes:

- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.